



# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**

[List multiple models if applicable.]

HP ProBook 450 G5 Notebook PC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm M/B, USB Board, Touchpad Module, Audio board	4
Batteries	All types including standard alkaline and lithium coin or button style batteries Battery cell & RTC	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords	Power cord	1
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		

Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Screwdriver	#1
Plum Screwdriver	T8
Description #3	
Description #4	
Description #5	

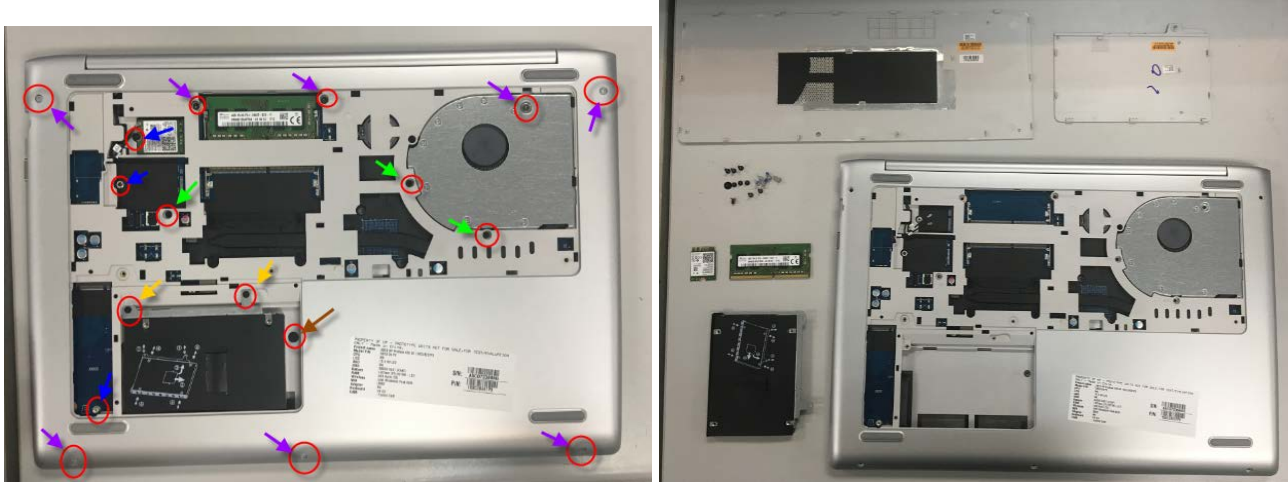
## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Relax the screw to disassembly RAM door
2. Relax the screw to disassembly HDD door
3. Remove screw\*2 to disassembly HDD assy
4. Remove screw\*3 to disassembly KB
5. Remove screw\*1 to disassembly Wlan module
6. Remove screw\*1 to disassembly Wwan module
7. Remove screw\*1 to disassembly SSD module
8. Remove screw\*9 to disassembly Top-assy and Base-assy
9. Remove FFC & connector on Base-assy: Power,TP module,Finger printer,Speaker
10. Removed screw\*2 to disassembly SD daughter board
11. Remove screw\*1 to disassembly battery
12. Remove USB daughter board on Base-assy
13. Remove screw\*1 to disassembly Fan
14. Remove screw\*1 to disassembly Type-C BKT
15. Remove screw\*3 to disassembly main board
16. Remove screw\*2 to disassembly speaker assy on Top-assy
17. Remove screw\*1 to disassembly power daughter board on Top-assy
18. Remove screw\*6 to disassembly TP module on Top-assy
19. Disassembly Bezel-assy with LCD Cover-assy
20. Remove screw\*4 to disassembly Panel on Cover-assy
21. Removed screw\*6 to disassembly hinge on Cover-assy
22. Removed screw\*4 to disassembly hinge on Base-assy
23. Removed Cable : LVDS、Antenna

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

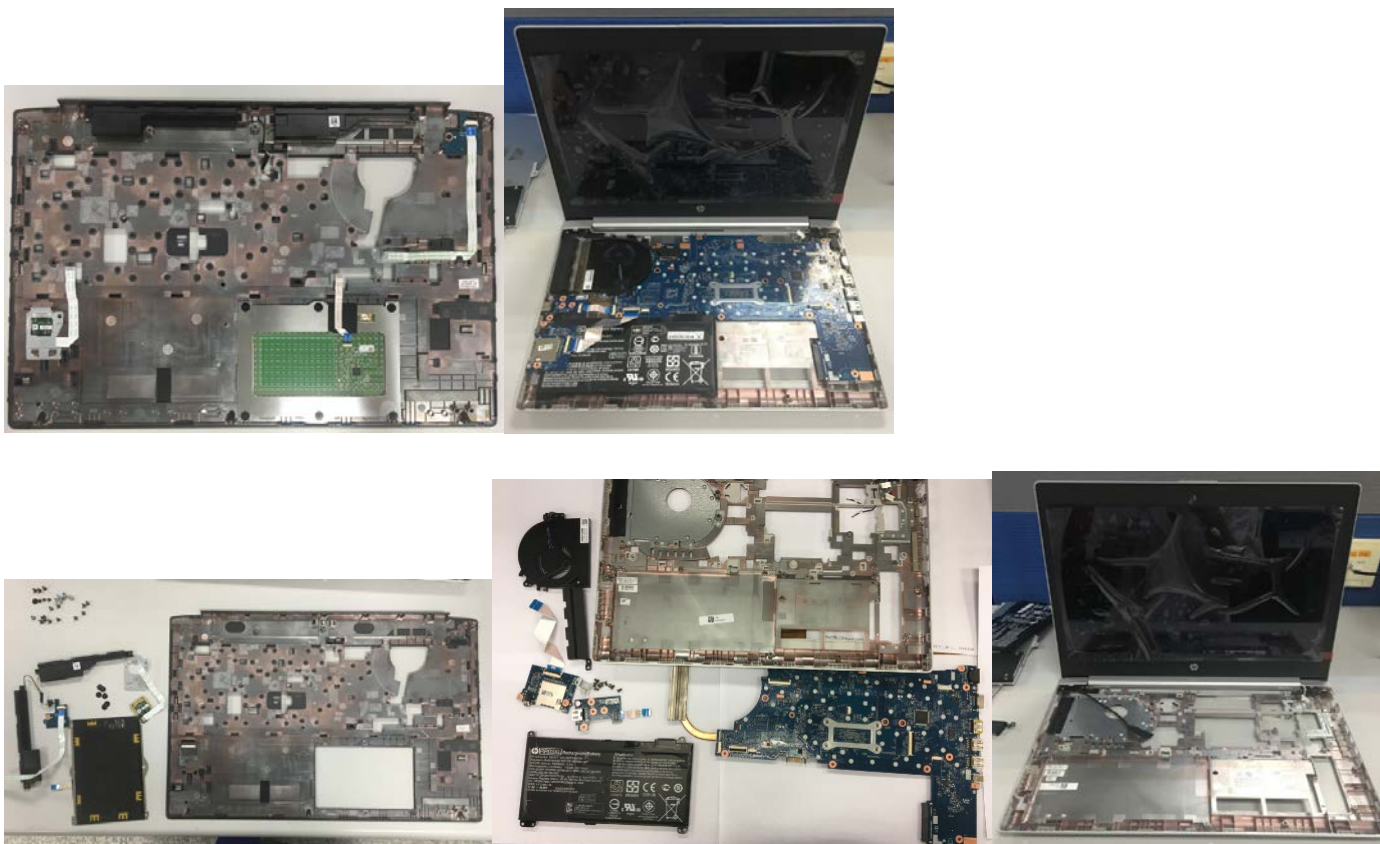
1. Remove screw to disassembly HDD, Wlan, Wwan, SSD, KB and base's screw.



2. Remove screw to disassembly Top and Base.



### 3. Top-assy & Base-assy disassembly



### 4. LCD module set disassembly

